



RE226-LF

- Epoxy fibre-glass FR4 1.50 mm
- Single-sided 35 µm Cu
- Hot air leveling (HAL-leadfree)
- Hole spacing 2.54 x 2.54 mm
- 35 x 42 soldering pads 2.10 mm Ø
- Hole dia 1.00 mm
- Connectors D-Sub DIN 41652 2 x 37-channel
- 2 potential strips
- Size 100 x 160 mm